

## Stretched SO8/SO6

### Mechanical and Environmental Testing

#### Description

The document's reliability data shown includes Broadcom® reliability test data from the reliability tests done on this product family. All of these products use similar processes and materials. The data in [Table 1](#) and [Table 2](#) reflect actual test data for the devices. Before stress, all devices are preconditioned at MSL 1 using a solder reflow process (260°C peak temperature) and 20 temperature cycles (–55°C to +125°C, 15 minutes dwell, 1 minute transfer). This data is taken from testing on Broadcom devices using internal Broadcom processes, material specifications, design standards, and statistical process controls.

**This data is not transferable to other manufacturer's similar part types.**

#### Definition of Failure

Abnormal resistance (meaning open or short failure) is the definition of failure in this data sheet. Specifically, failure occurs when the device fails contact resistance either high or low, or both, and/or when the device experiences abnormal leakages, or both.

#### Reliability Testing

Broadcom subjects the devices to a series of reliability tests (including environmental, mechanical, and electrical tests) to ensure they meet the intended reliability expectation. The following tables show the results of reliability testing conducted by Broadcom over a period of time (as shown in the test conditions).

**Table 1: Mechanical Tests (Testing Done on a Constructional Basis)**

| Test Name                      | Reference Standard    | Test Conditions   | Units Tested | Units Failed |
|--------------------------------|-----------------------|---|--------------|--------------|
| Temperature Cycling'           | JESD-A104             | –55°C to 125°C, Transfer = 1 minute, Dwell = 15 minutes, 1000 cycles  | 5267         | 0            |
| Temperature Cycling            | JESD-A104             | –65°C to 150°C, Transfer = 1 minute, Dwell = 15 minutes, 500 cycles   | 596          | 0            |
| Solderability (RoHS condition) | JESD-B102             | 8 hours steam aging (93°C), followed by solder dip (260°C, 5 seconds) | 131          | 0            |
| Physical Dimensions            | JESD-B100             | Conformance to data sheet package drawings                            | 20           | 0            |
| Preconditioning                | JESD-020<br>JESD-A113 | As per reference standard (to conform to MSL 1)                       | 19,930       | 0            |

**Table 2: Environmental Tests (Testing Done on a Constructional Basis)**

| Test Name                 | Reference Standard | Test Conditions  | Units Tested | Units Failed |
|---------------------------|--------------------|--|--------------|--------------|
| Temperature-Humidity-Bias | JESD-A101          | $T_A = 85^{\circ}\text{C}$ , RH = 85%, Biased, Time = 1000 hours   | 118          | 0            |
| HAST                      | JESD-A110          | $T_A = 130^{\circ}\text{C}$ , RH = 85%, Biased, Time = 96 hours    | 3157         | 0            |
| Unbiased HAST             | JESD-A118          | $T_A = 130^{\circ}\text{C}$ , RH = 85%, Unbiased, Time = 96 hours  | 2349         | 0            |
| Autoclave                 | JESD-A102          | $T_A = 121^{\circ}\text{C}$ , RH = 100%. Unbiased, Time = 96 hours | 984          | 0            |
| High Temperature Bake     | JESD-A103          | $T_A = 150^{\circ}\text{C}$ , Unbiased, Time = 1000 hours          | 2830         | 0            |

## Disclaimer

Broadcom reserves the right to modify the data and is correct at the time of release

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